

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE3400 uses advanced trench technology to provide excellent $R_{\rm DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

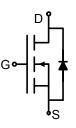
• $V_{DS} = 30V, I_{D} = 5.8A$

 $R_{DS(ON)}$ < 57m Ω @ V_{GS} =2.5V

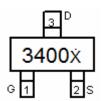
 $R_{DS(ON)}$ < 41m Ω @ V_{GS} =4.5V

 $R_{DS(ON)}$ < 35m Ω @ V_{GS} =10V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package
- PWM applications
- Load switch
- Power management



Schematic diagram



Marking and pin assignment



SOT-23 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
3400 ×	NCE3400	SOT-23	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±12	V
Drain Current-Continuous	I _D	5.8	Α
Drain Current-Pulsed (Note 1)	I _{DM}	30	Α
Maximum Power Dissipation	P _D	1.4	W
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	$^{\circ}\!$

Thermal Characteristic

Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30	33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA



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Gate-Body Leakage Current	I _{GSS}	V_{GS} =±12 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=250\mu A$	0.7	0.9	1.2	V
	ance R _{DS(ON)}	V _{GS} =2.5V, I _D =4A	-	28	57	mΩ
Drain-Source On-State Resistance		V_{GS} =4.5V, I_D =5A	-	24	41	mΩ
		V _{GS} =10V, I _D =5A	-	22	35	mΩ
Forward Transconductance	g FS	V_{DS} =5 V , I_D =5 A	10	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	V _{DS} =15V,V _{GS} =0V,	-	820	-	PF
Output Capacitance	Coss	V _{DS} -13V,V _{GS} -0V, F=1.0MHz	-	99	-	PF
Reverse Transfer Capacitance	C _{rss}	r – 1.0ivii iz	-	77	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	3.3	-	nS
Turn-on Rise Time	t _r	V_{DD} =15V, R_L =2.7 Ω	-	4.8	-	nS
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =10 V , R_{GEN} =3 Ω	-	26	-	nS
Turn-Off Fall Time	t _f		-	4	-	nS
Total Gate Charge	Qg	\/ -45\/ -50	-	9.5	-	nC
Gate-Source Charge	Q_{gs}	V_{DS} =15V, I_{D} =5A, V_{GS} =4.5V	-	1.5	-	nC
Gate-Drain Charge	Q_{gd}	V _{GS} -4.5V	-	3	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =5A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	5.8	Α

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- **3.** Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

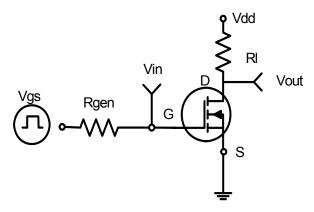


Figure 1:Switching Test Circuit

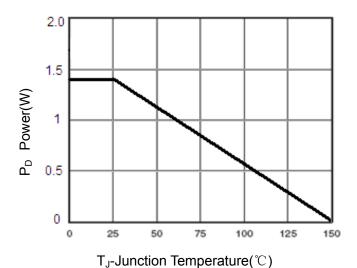


Figure 3 Power Dissipation

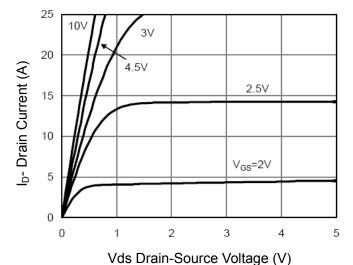


Figure 5 Output Characteristics

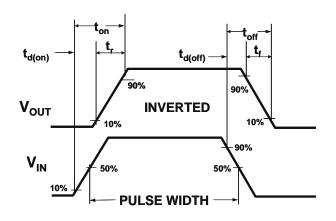


Figure 2:Switching Waveforms

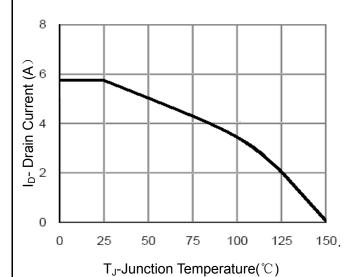
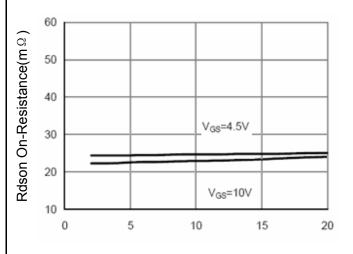


Figure 4 Drain Current



I_D- Drain Current (A) Figure 6 Drain-Source On-Resistance



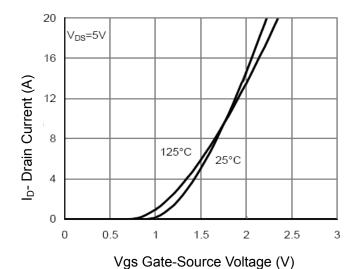
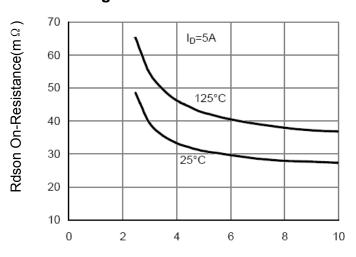


Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs

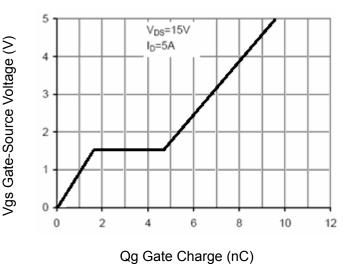


Figure 11 Gate Charge

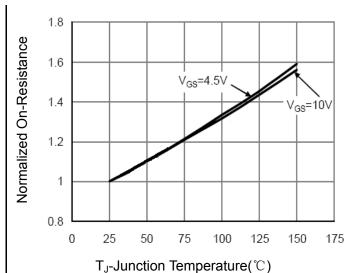


Figure 8 Drain-Source On-Resistance

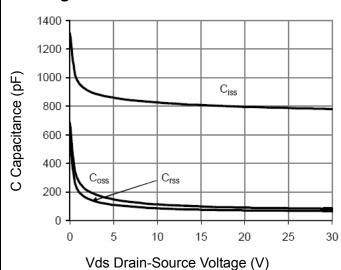


Figure 10 Capacitance vs Vds

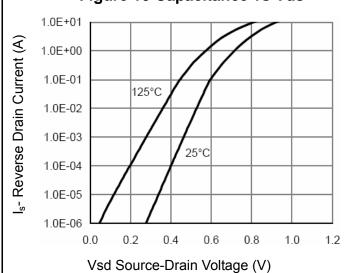


Figure 12 Source- Drain Diode Forward



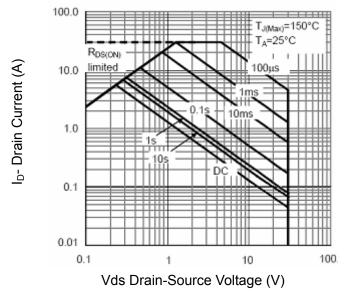


Figure 13 Safe Operation Area

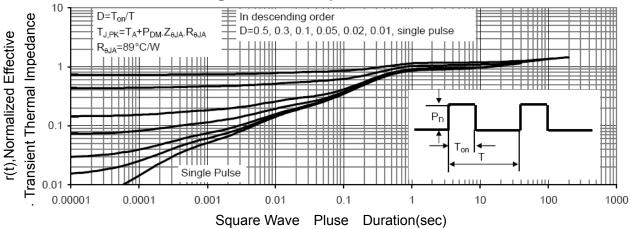
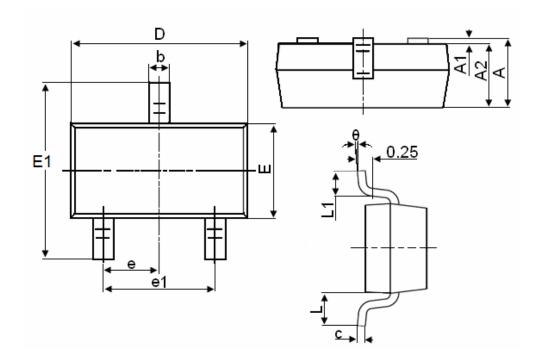


Figure 14 Normalized Maximum Transient Thermal Impedance



SOT-23 Package Information



Symbol	Dimensions in Millimeters			
	MIN.	MAX.		
Α	0.900	1.150		
A1	0.000	0.100		
A2	0.900	1.050		
b	0.300	0.500		
С	0.080	0.150		
D	2.800	3.000		
E	1.200	1.400		
E1	2.250	2.550		
е	0.950TYP			
e1	1.800	2.000		
L	0.550REF			
L1	0.300	0.500		
θ	0°	8°		

Notes

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- 5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.



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